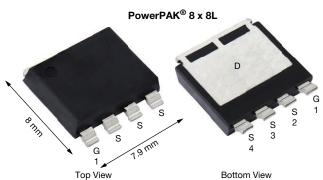
RoHS

COMPLIANT

HALOGEN FREE



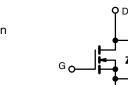
N-Channel 80 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	80				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.00135				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 7.5 \text{ V}$	0.00158				
Q _g typ. (nC)	103				
I _D (A) ^a	302				
Configuration	Single				

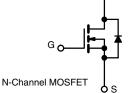
FEATURES

- TrenchFET® Gen V power MOSFET
- Fully lead (Pb)-free device
- Very low R_{DS} x Q_g figure of merit (FOM)
- Up to 302 A maximum continuous drain current
- 50 % smaller footprint than D2PAK (TO-263)
- 100 % R_a and UIS tested
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



APPLICATIONS

- · Synchronous rectification
- OR-ing
- Motor drive control
- · Battery management



ORDERING INFORMATION	
Package	PowerPAK 8 x 8L
Lead (Pb)-free and halogen-free	SIJH5800E-T1-GE3
ABSOLUTE MAXIMUM RATINGS ($T_A = 25 ^{\circ}$ C	, unless otherwise noted)

ABSOLUTE MAXIMUM RATING	iS (T _A = 25 °C, u	nless other	wise noted)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	80	V	
Gate-source voltage		V_{GS}	±20	7 v	
Continuous drain current (T _J = 175 °C)	T _C = 25 °C		302		
	T _C = 70 °C	1 .	253	7	
	T _A = 25 °C	I _D	30 b	İ	
	T _A = 70 °C		25 ^b	A	
Pulsed drain current (t = 100 μs)		I _{DM}	500	1 ^	
Continuous source drain diade current	T _C = 25 °C	,	303	7	
Continuous source-drain diode current	T _A = 25 °C	l _S	3 b	7	
Single pulse avalanche current		I _{AS}	75	7	
Single pulse avalanche energy L = 0.1 mH		E _{AS}	281	mJ	
	T _C = 25 °C		333	W	
Maximum power dissipation	T _C = 70 °C	В	233		
	T _A = 25 °C	P _D	3.3 b		
	T _A =70 °C		2.3 b		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature) ^c			260	1	

THERMAL RESISTANCE RATING	as				
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^b	Steady state	R _{thJA}	36	45	°C/W
Maximum junction-to-case (drain)	Steady state	R _{thJC}	0.36	0.45	0/ ٧٧

Notes

a. $T_C = 25$ °C

b. Surface mounted on 1" x 1" FR4 board
 c. See solder profile (www.vishay.com/doc?73257). The PowerPAK 8 x 8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
 d. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components



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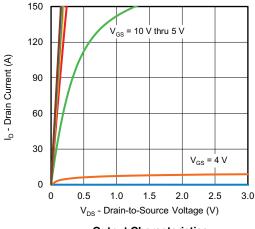
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V_{DS}	V _{GS} = 0 V, I _D = 1 mA	80	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = 10 mA	-	36	-	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-9.7	-	mV/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	-	4	V
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20$	-	-	100	nA
Zero gate voltage drain current		V _{DS} = 64 V, V _{GS} =0 V	-	-	1	
	I _{DSS}	V _{DS} = 64 V, V _{GS} = 0 V, T _J = 70 °C	-	-	15	μA
Duning and the second of the s	Б	V _{GS} = 10 V, I _D = 20 A	-	0.00097	0.00135	0
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 7.5 V, I _D = 20 A	-	0.0012	0.00158	Ω
Forward transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 75 A	-	170	-	S
Dynamic ^b						
Input capacitance	C _{iss}		-	7730	-	
Output capacitance	C _{oss}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	2442	-	рF
Reverse transfer capacitance	C _{rss}		-	20	-	
Total gate charge	Q _g	$V_{DS} = 40 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	V, V _{GS} = 10 V, I _D = 20 A -		155	
			-	78	120	nC
Gate-source charge	Q_{gs}	$V_{DS} = 40 \text{ V}, V_{GS} = 7.5 \text{ V}, I_D = 20 \text{ A}$	_	35	-	
Gate-drain charge	Q _{gd}		-	11	-	
Gate resistance	R_g	f = 1 MHz	0.34	1.7	3.4	Ω
Turn-on delay time	t _{d(on)}		-	20	40	
Rise time	t _r	$V_{DD} = 40 \text{ V}, R_L = 4 \Omega, I_D \cong 10 \text{ A},$		16	35	
Turn-off delay time	t _{d(off)}	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	53	100	1
Fall time	t _f		-	27	60	
Turn-on delay time	t _{d(on)}		-	25	50	ns
Rise time	t _r	$V_{DD} = 40 \text{ V}, R_L = 4 \Omega, I_D \cong 10 \text{ A},$	-	28	60	
Turn-off delay time	t _{d(off)}	$V_{GEN} = 7.5 \text{ V}, R_g = 1 \Omega$	-	48	100	
Fall time	t _f		-	27	60	
Drain-Source Body Diode Characteristi	cs					
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	303	_
Pulse diode forward current	I _{SM}		-	-	500	Α
Body diode voltage	V_{SD}	I _S = 10 A, V _{GS} = 0 V	-	0.72	1.1	V
Body diode reverse recovery time	t _{rr}		-	106	210	ns
Body diode reverse recovery charge	Q _{rr}	1 10 A dl/d+ 100 A/va T 05 °C	-	190	380	nC
Reverse recovery fall time	ta	I _F = 10 A, dl/dt = 100 A/μs, T _J = 25 °C		55	-	
Reverse recovery rise time	t _b		-	51	-	ns

Notes

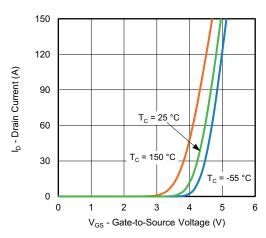
- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

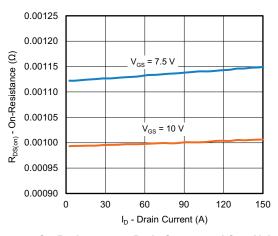




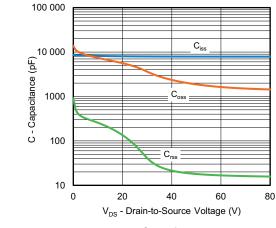
Output Characteristics



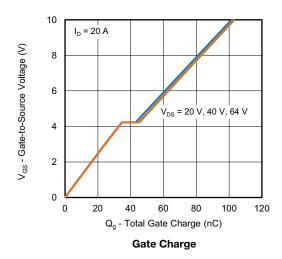
Transfer Characteristics

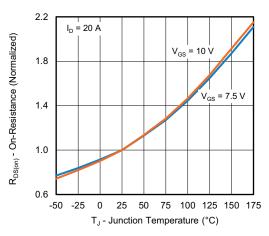


On-Resistance vs. Drain Current and Gate Voltage



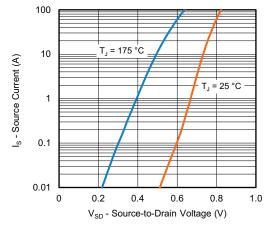
Capacitance



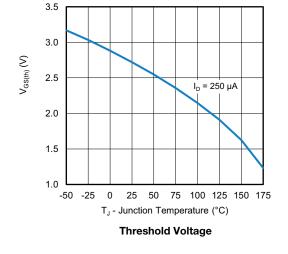


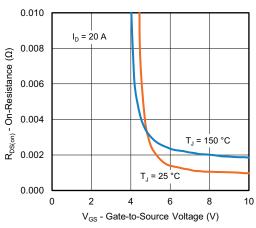
On-Resistance vs. Junction Temperature



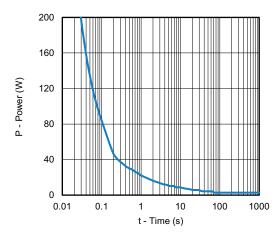


Source-Drain Diode Forward Voltage

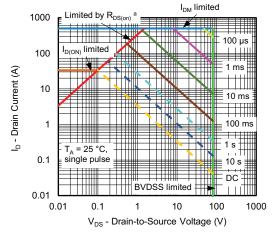




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

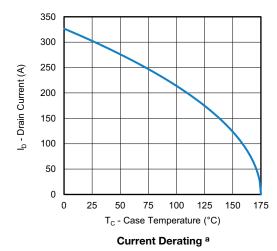


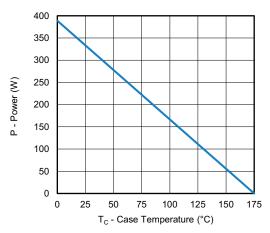
Safe Operating Area, Junction-to-Ambient

Note

a. $V_{GS} > minimum V_{GS}$ at which $R_{DS(on)}$ is specified





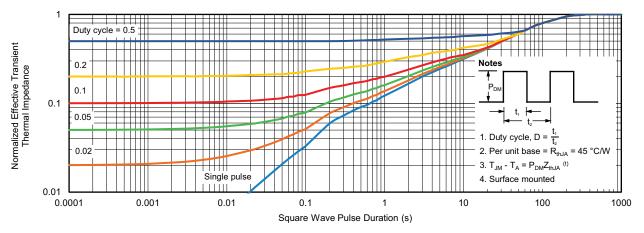


Power, Junction-to-Case

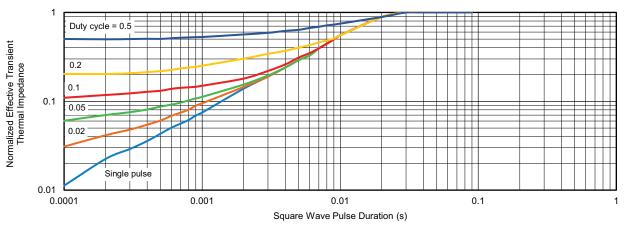
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



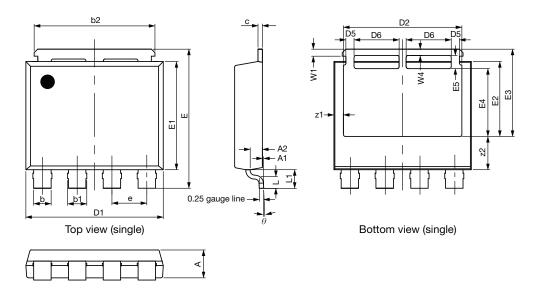
Normalized Thermal Transient Impedance, Junction-to-Case

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PowerPAK® 8 x 8L BWL Case Outline 2



DIM	MILLIMETERS		INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
Α	1.50	1.60	1.70	0.059	0.063	0.067
A1	0.00	-	0.127	0.000	-	0.005
A2	0.655	0.705	0.755	0.026	0.028	0.030
b	0.92	1.00	1.08	0.036	0.039	0.043
b1	1.02	1.10	1.18	0.040	0.043	0.046
b2	6.84	6.94	7.04	0.269	0.273	0.277
С	0.20	0.25	0.30	0.008	0.010	0.012
D1	7.80	7.90	8.00	0.307	0.311	0.315
D2	6.70	6.80	6.90	0.264	0.268	0.272
D5	0.37	0.47	0.57	0.015	0.019	0.022
D6	2.49	2.59	2.69	0.098	0.102	0.106
е	1.97	2.00	2.03	0.078	0.079	0.080
E	7.90	8.00	8.10	0.311	0.315	0.319
E1	6.12	6.22	6.32	0.241	0.245	0.249
E2	4.21	4.31	4.41	0.166	0.170	0.174
E3	4.92	5.02	5.12	0.194	0.198	0.202
E4	3.80	3.90	4.00	0.150	0.154	0.157
E5	0.65	0.75	0.85	0.026	0.030	0.033
L	0.61	0.68	0.75	0.024	0.027	0.030
L1	1.00	1.07	1.15	0.039	0.042	0.045
W1	0.30	0.40	0.50	0.012	0.016	0.020
W4	0.32	0.37	0.42	0.013	0.015	0.017
z1	0.45	0.55	0.65	0.018	0.022	0.026
z2	1.81	1.91	2.01	0.071	0.075	0.079
θ	0°	-	5°	0°	-	5°

ECN: S19-0643-Rev. B, 05-Aug-2019

DWG: 6073

Note

Millimeter will govern

Revison: 05-Aug-2019 1 Document Number: 79736



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